

Title (en)

FILM ARRANGEMENT WITH INCREASED TEMPERATURE RESISTANCE

Title (de)

FOLIENANORDNUNG MIT ERHÖHTER TEMPERATURBESTÄNDIGKEIT

Title (fr)

AGENCEMENT DE FEUILLES AVEC UNE PLUS GRANDE RÉSISTANCE THERMIQUE

Publication

**EP 2576210 A1 20130410 (DE)**

Application

**EP 11727654 A 20110524**

Priority

- DE 102010021453 A 20100525
- EP 2011058483 W 20110524

Abstract (en)

[origin: WO2011147835A1] An embodiment of the invention relates to a film arrangement (1) with a temperature resistance of up to at least 70 °C, comprising - at least one biologically degradable base layer (5), which comprises a polyhydroxycarboxylic acid or starch, with a proportion of at least 50 wt.% of the film arrangement, said base layer having a temperature resistance of no more than 60 °C, and - at least one first temperature-resistant film layer (10) that comprises a polymer that is different from the base layer, said temperature-resistant film layer having a glass transition temperature of at least 70 °C, and/or a crystallization degree of at least 10% and a melting point of at least 70 °C. Such a film arrangement has an increased temperature resistance with respect to the biologically degradable base layer (5) but still has a sufficient degree of biological degradability and compostability as a result of the base layer.

IPC 8 full level

**B32B 9/02** (2006.01); **B32B 7/12** (2006.01); **B32B 27/08** (2006.01); **B32B 27/28** (2006.01); **B32B 27/32** (2006.01); **B32B 27/34** (2006.01);  
**B32B 27/36** (2006.01)

CPC (source: EP)

**B32B 7/12** (2013.01); **B32B 9/02** (2013.01); **B32B 27/08** (2013.01); **B32B 27/28** (2013.01); **B32B 27/306** (2013.01); **B32B 27/32** (2013.01);  
**B32B 27/34** (2013.01); **B32B 27/36** (2013.01); **C08L 3/02** (2013.01); **B32B 2307/306** (2013.01); **B32B 2307/308** (2013.01);  
**B32B 2307/412** (2013.01); **B32B 2307/5825** (2013.01); **B32B 2307/702** (2013.01); **B32B 2307/704** (2013.01); **B32B 2307/7163** (2013.01);  
**B32B 2307/732** (2013.01)

Citation (search report)

See references of WO 2011147835A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**DE 102010021453 A1 20111201**; EP 2576210 A1 20130410; WO 2011147835 A1 20111201

DOCDB simple family (application)

**DE 102010021453 A 20100525**; EP 11727654 A 20110524; EP 2011058483 W 20110524